



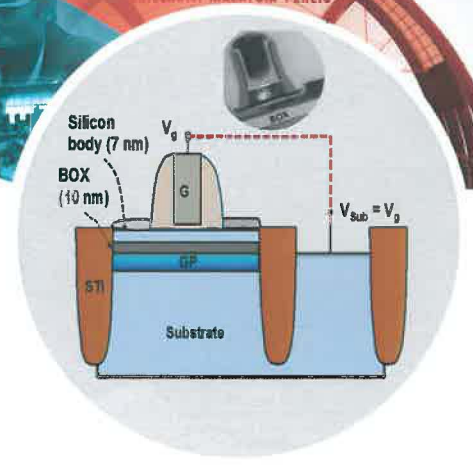
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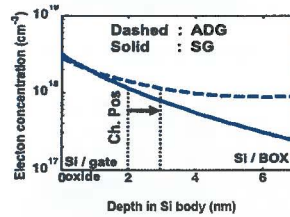
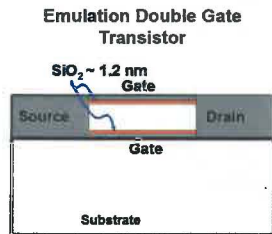
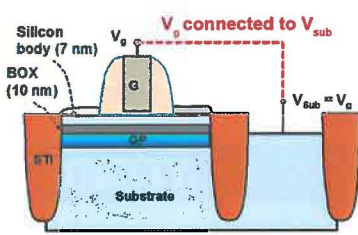
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# ASYMMETRICAL DOUBLE GATE: SIGNIFICANT IMPROVEMENT IN ULTRA-SCALED SOI MOSFET

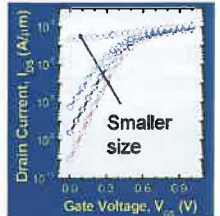


## INTRODUCTION

Fully-depletion operation is mandatory requirement for ultra-scaled devices (i.e. < 45 nm technology) which only can be achieved either multi-gate (i.e. FinFET) or thin body Silicon-on-Insulator (SOI). Thin body SOI offers another interesting feature compared to any other technologies i.e. back-gate biasing. In this invention, we utilize asymmetrical contact from the top which provide improved performance and better controlled of short-channel effects in thin body and thin buried oxide of SOI MOSFETs.



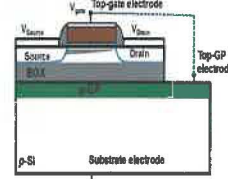
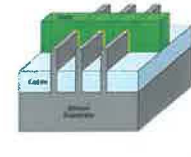
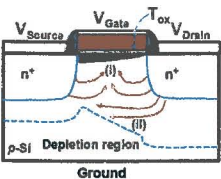
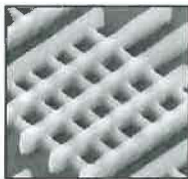
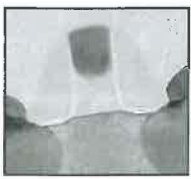
### Short Channel Effects



## NOVELTY

### Existing Technologies

### New Invention



Planar Architecture - Silicon Platform

3D Architecture - Silicon/SOI Platform

Planar Architecture - SOI Platform

- Simple architecture with significant Improvement on drive current ( $I_d$ - $V_g$  and  $I_d$ - $V_d$ ) without forgo the off current.
- Extension to ultra-scaled devices : support Moore's Law for ~ 10 nm technology
- Eliminate Short Channel Effects

### Collaboration

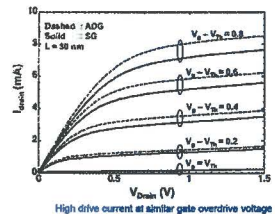
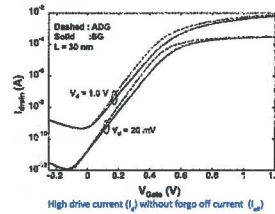
- Université catholique de Louvain, Louvain-la-neuve, Belgium
- CEA - Leti, Grenoble, France

### PUBLICATIONS

- M.K. Md Arshad et al, Solid-State Electronics, 2014 (accepted for publication)
- M.K. Md Arshad et al, Solid-State Electronics, 90, 2013: 56-64
- M.K. Md Arshad et al, IEEE Trans. Electron Devices, 59, 2012: 247-251
- M.K. Md Arshad et al, Solid-State Electronics, 90, 2012: 50-58
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## RESULTS

### I-V Characteristics



## COMMERCIALIZATION POTENTIAL

*22 nm gate length	Single Gate	Asymmetrical Double Gate.	% improvement
$V_{Th}$ (V)	0.45	0.30	30 %
SS (mV/dec)	95	80	15 %
DIBL (mV/V)	115	95	18 %
$I_{on}$ (uA/um)	500	620	24 %

- Lower threshold voltage (i.e suitable for low power application -energy saving)
- Lower subthreshold slope (i.e faster switching speed between on and off),
- Lower drain-induced barrier lowering (i.e. better control of short channel effects : translated into ~ 20 % increased in speed.

### PRODUCT IMPLEMENTATION



Low power mobile application i.e. smart phone.